

Data sheet acquired from Harris Semiconductor SCHS201C

February 1998 - Revised October 2003

# High-Speed CMOS Logic 14-Stage Binary Counter

### Features

- Fully Static Operation
- Buffered Inputs
- Common Reset
- Negative Edge Clocking
- Fanout (Over Temperature Range)
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity: N<sub>IL</sub> = 30%, N<sub>IH</sub> = 30% of V<sub>CC</sub> at V<sub>CC</sub> = 5V
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,
     V<sub>IL</sub>= 0.8V (Max), V<sub>IH</sub> = 2V (Min)
  - CMOS Input Compatibility, I<sub>I</sub>  $\leq$  1 $\mu$ A at V<sub>OL</sub>, V<sub>OH</sub>

### Description

The 'HC4020 and 'HCT4020 are 14-stage ripple-carry binary counters. All counter stages are master-slave flipflops. The state of the stage advances one count on the negative clock transition of each input pulse; a high voltage level on the MR line resets all counters to their zero state. All inputs and outputs are buffered.

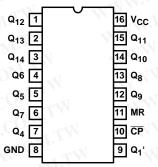
### **Ordering Information**

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC4020F3A	-55 to 125	16 Ld CERDIP
CD54HCT4020F3A	-55 to 125	16 Ld CERDIP
CD74HC4020E	-55 to 125	16 Ld PDIP
CD74HC4020M	-55 to 125	16 Ld SOIC
CD74HC4020MT	-55 to 125	16 Ld SOIC
CD74HC4020M96	-55 to 125	16 Ld SOIC
CD74HCT4020E	-55 to 125	16 Ld PDIP
CD74HCT4020M	-55 to 125	16 Ld SOIC
CD74HCT4020MT	-55 to 125	16 Ld SOIC
CD74HCT4020M96	-55 to 125	16 Ld SOIC

NOTE: When ordering, use the entire part number. The suffix 96 denotes tape and reel. The suffix T denotes a small-quantity reel of 250.

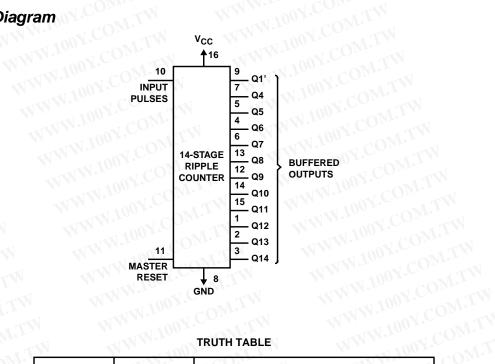
### **Pinout**

CD54HC4020, CD54HCT4020 (CERDIP) CD74HC4020, CD74HCT4020 (PDIP, SOIC) TOP VIEW



### Functional Diagram

by.COM.TW



### TRUTH TABLE

COUNT	MR	OUTPUT STATE
<b>√</b> ↑	WIL	No Change
1	WEN.	Advance to Next State
X	H	All Outputs Are Low

WWW.100Y.COM.TW

特力材料886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www. 100y. com. tw

WWW.10

WWW.100Y.COM.TW

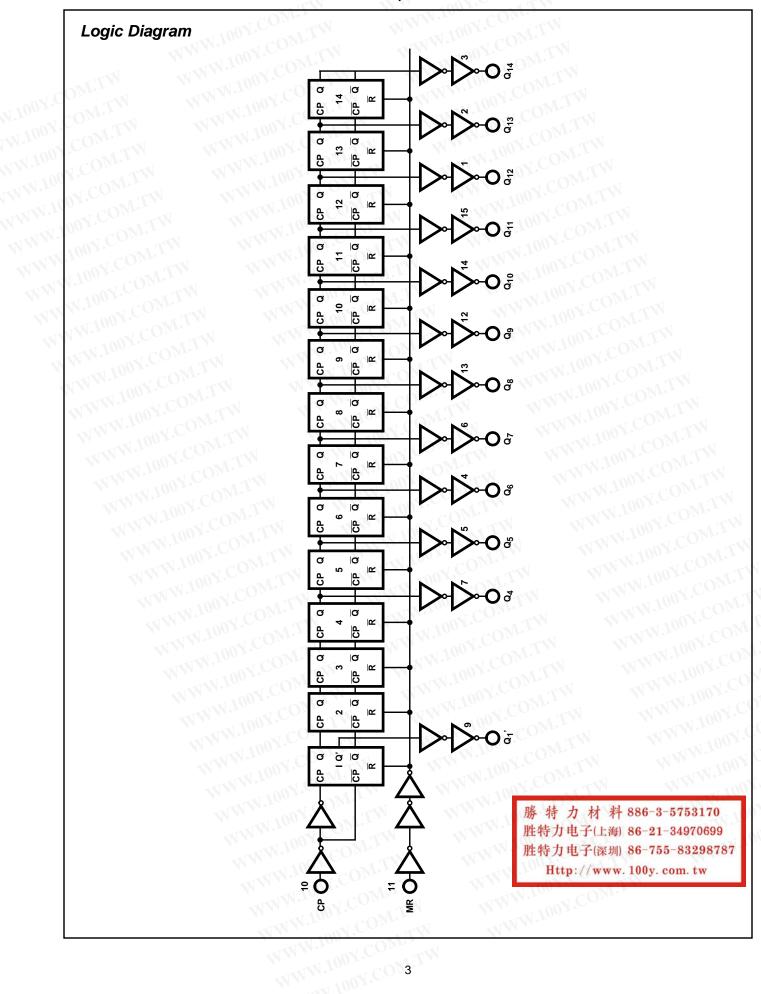
oy.coM

WW.100Y.COM.TW

WWW.100Y.CO

ov.com.TW

 $<sup>\</sup>uparrow$  = Transition from Low to High Level,  $\downarrow$  = Transition from High to Low.



### **Absolute Maximum Ratings** DC Supply Voltage, V<sub>CC</sub> .....-0.5V to 7V DC Input Diode Current, I<sub>IK</sub> For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ .....±20mA DC Output Diode Current, IOK For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ ......±20mA DC Output Source or Sink Current per Output Pin, IO For V<sub>O</sub> > -0.5V or V<sub>O</sub> < V<sub>CC</sub> + 0.5V ......±25mA DC V<sub>CC</sub> or Ground Current, I<sub>CC or</sub> I<sub>GND</sub> .....±50mA **Operating Conditions** Temperature Range (T<sub>A</sub>) .....-55°C to 125°C

### **Thermal Information**

Thermal Resistance (Typical, Note 1)	$\theta_{JA}$ (oC/W)
E (PDIP) Package	67
M (SOIC) Package	
Maximum Junction Temperature	
Maximum Storage Temperature Range	-65°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300°C
(SOIC - Lead Tips Only)	

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

upply Voltage Range, V<sub>CC</sub>
HC Types ......2V to 6V Supply Voltage Range, V<sub>CC</sub> DC Input or Output Voltage, V<sub>I</sub>, V<sub>O</sub> ...... 0V to V<sub>CC</sub> Input Rise and Fall Time

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

4.5V..... 500ns (Max) 

### **DC Electrical Specifications**

WWW.100Y.C	OM.TV		TEST CONDITIONS		1.CO	25°C	<b>1</b>	-40°C 1	го 85 <sup>0</sup> С	-55°C TO 125°C		LINITS
PARAMETER	SYMBOL	V <sub>I</sub> (V)	I <sub>O</sub> (mA)	V <sub>CC</sub> (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES			M	-x11(	01.	M. <sup>7</sup>	M		N V	11007	a o N	1.7.
High Level Input	CVIH	TW-	- W	2	1.5	<u> </u>		1.5	Min	1.5	.U <u>-</u>	V
Voltage	LI COM			4.5	3.15	$\mathbb{C}_{G_{M_2}}$	W	3.15	W	3.15	N.CO	V
W 10	(O)	I'I		6	4.2	$co_1$	1	4.2	-31	4.2	N.C	A
Low Level Input	V <sub>IL</sub>	W.E.M.	-	2	11.7 <del>0</del> 0.	0	0.5	-	0.5	N.V.	0.5	O.A.
Voltage	100 Y.CC	TIV		4.5	31700	1.0	1.35	N -	1.35	TXN	1.35	V
MMM	· COV.C	$O_{Mr}$	N	6	11.	OY-C	1.8	- N	1.8	111	1.8	٧
High Level Output	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	2	1.9	. V.	Oh.	1.9	-	1.9		
Voltage CMOS Loads	1.1001	COM.	-0.02	4.5	4.4	47	CON	4.4	-	4.4	N.Fo.	V
OWIGO Louds	TX 1007	Mon	-0.02	6	5.9	700,	<u>-</u> 01	5.9	-	5.9	M=10	V
High Level Output	100	Y.Co.	TEN	- 1	N Ni	KI 1700	1.0	MªTV	-	3/1 4	- x 1	V
Voltage TTL Loads	WWW.TOOY.CO	M.CON	-4	4.5	3.98	-10	N.C.	3.84	N -	3.7	N .	OOV.
112 20000	MW.Iu	CO.	-5.2	6	5.48	M. In	O.V.C	5.34	TV-	5.2	11-11.	V
Low Level Output	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	2	-	NAY.	0.1	.O <u>.</u>	0.1	-	0.1	V
Voltage CMOS Loads	MAN	100 X.	0.02	4.5	-7//	- TN	0.1	COM	0.1	-	0.1	V
OMOO Loado	MMM	100Y.	0.02	6	- 1	NA	0.1	-01	0.1	-	0.1	V
Low Level Output	WWV	You	CO.	TV			100	Y.Co.	VT-	-	411	V
Voltage TTL Loads		W.700	4	4.5	-	WW	0.26	W.Cl	0.33	N -	0.4	V
112 20000	N	JW.100	5.2	6	-	-11	0.26	-\$1 C	0.33	-xXI	0.4	V
Input Leakage Current	l <sub>l</sub> N	V <sub>CC</sub> or GND	ON.CC	6	- N	W	±0.1	00 X	±1/	TW	±1	μА
Quiescent Device Current	Icc	V <sub>CC</sub> or GND	0, C	6	W-	-	8	1007	80	WTI	160	μА

### DC Electrical Specifications (Continued)

W	NW.100	CONDI	- / / /	V <sub>CC</sub>	MAIN.	25°C	V.C	-40°C 1	O 85°C	-55°C T	O 125°C	
PARAMETER	SYMBOL	V <sub>I</sub> (V)	I <sub>O</sub> (mA)	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HCT TYPES	N	1001.	OMIT	-		-TXN.	100 1.	Mos	T.A.	•	•	
High Level Input Voltage	V <sub>IH</sub>	100-X'C	T.MO.	4.5 to 5.5	2	W.	100X	2	T.W	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	N.100.2	$co_M$	4.5 to 5.5	-	WW	0.8	N.CO	0.8	N -	0.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	WW	NW.1	4.4	OM	4.4	-	V
High Level Output Voltage TTL Loads	1	MM'I	-4.C	4.5	3.98	- 7	NINA M-M	3.84	I'CO <sub>J</sub>	3.7	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	TW	-	0.1	N.10	0.1	om.T	0.1	V
Low Level Output Voltage TTL Loads	LA N	WW	W.4	4.5	M.TV	N -	0.26	MM.	0.33	$C_{OM}$	0.4	V
Input Leakage Current		V <sub>CC</sub> and GND	0 1	5.5	$OV_{T-1}$	CM	±0.1	WW	)±1	Y.COD	±1	μА
Quiescent Device Current	Icc	V <sub>CC</sub> or GND	0	5.5	COM	TW	8	1	80	N.CO	160	μА
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI <sub>CC</sub> (Note 2)	V <sub>CC</sub> -2.1	MM	4.5 to 5.5	V.CO	100	360	M	450	100 X.	490	μА

### HCT Input Loading Table

INPUT	UNIT LOADS
MR	0.65
СР	. 0.5 WN

NOTE: Unit Load is  $\Delta I_{CC}$  limit specified in DC Electrical Table, e.g., 360μA max at 25°C.

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

### **Prerequisite for Switching Specifications**

PARAMETER	1007.0	$M_{\perp}T_{\parallel}$	25	°C	-40°C 7	ГО 85 <sup>0</sup> С	-55°C T	O 125°C	1700
	SYMBOL	V <sub>CC</sub> (V)	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES	M. CONT.C	TY		MM	-1100Y			MA	-x1 10
Maximum Input Pulse	f <sub>MAX</sub>	2	6	WW	5	Com	4	-11/1	MHz
Frequency	M.100	4.5	30	-WV	25	$^{A'C_{\mathbf{O}_{D_{A}}}}$	20	- 1	MHz
	WW.100	6	35	-	29	W.CO	24	-	MHz
Input Pulse Width	t <sub>W</sub>	2	80	- 7/	100	√ CC	120	-	ns
	WW. 70	4.5	16	-	20	00 5.	24	<b>-</b>	ns
	WWW	6	14	-	17	100.7.	20	-	ns

WWW.100Y.CO.

<sup>2.</sup> For dual-supply systems theoretical worst case ( $V_I = 2.4V$ ,  $V_{CC} = 5.5V$ ) specification is 1.8mA.

### Prerequisite for Switching Specifications (Continued)

MM	1001.00	TW	25	°C	-40°C	ГО 85 <sup>0</sup> С	-55°C T	O 125°C	
PARAMETER	SYMBOL	V <sub>CC</sub> (V)	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
Reset Removal Time	t <sub>REM</sub>	2	50	MANN	65	11	75	-	ns
	W.Inc	4.5	10	WW	13	COL	15	-	ns
	M.100 r.	C(6)	9	- 1	11	$^{\Lambda}$ CO $_{M_T}$	13	-	ns
Reset Pulse Width	t <sub>W</sub>	2	80		100	-1 CON	120	-	ns
	W 100	4.5	16	- 11	20	0.5.	24	-	ns
	WW 110	6	14	- 17	17	00 x	20	-	ns
HCT TYPES	MM	OOY.CO	WILL		MAN	1007.	M.T.	N	
Maximum Input Pulse Frequency	f <sub>MAX</sub>	4.5	25	-	20	1.100Y.	16	N -	MHz
Input Pulse Width	t <sub>W</sub>	4.5	20	-	25	W.700.	30	- XĪ	ns
Reset Recovery Time	t <sub>REC</sub>	4.5	10	- 1	13	W.100	15	Lin	ns
Reset Pulse Width	t <sub>W</sub>	4.5	20	TW	25	T 10	30	T.T.W	ns

## Switching Specifications Input $t_r$ , $t_f = 6ns$

TI 100Y.CONLITY		TEST	V <sub>CC</sub>	T.IV	25°C		-40°C 1	O 85°C	-55°C TO 125°C		
PARAMETER	SYMBOL	CONDITIONS	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES	cW	MM	any.C	,0-	TW	•	MA	110	OX	Time	N
Propagation Delay Time (Figure 1)	t <sub>PLH,</sub>	C <sub>L</sub> = 50pF	2	$C_{G_{2n}}$	LTW	140	W	175	007.C	210	ns
CP to Q1' Output	WILL	MM	4.5		M-T	28	- 1	35	$10_{0.7}$	42	ns
	WILL	C <sub>L</sub> =15pF	5 00	N.C.	11	W_	- 1	N V	11907	ON	ns
	WT	C <sub>L</sub> = 50pF	6	07.C	- N	24	-	30	100	36	ns
Q <sub>n</sub> to Q <sub>n</sub> + 1	t <sub>PLH</sub> ,	C <sub>L</sub> = 50pF	2	OF.	COL	75	-	95	- 10	110	ns
WWW.Ioo	t <sub>PHL</sub>	N V	4.5	<u> </u>	$C_{\overline{O}_{L}}$	15	· -	19	111	22	ns
	COM.	C <sub>L</sub> =15pF	5	100	6	Mr.	W -	- 17	M.M.	ON Y.C	ns
W. 100	COM.	C <sub>L</sub> = 50pF	6	1.700	√.C	13		16		19	ns
MR to Q <sub>n</sub>	t <sub>PLH,</sub> t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	W=10	0 <u>-</u> -≼1 (	170	- XX	215	TVV	255	ns
			4.5	. W.	00 <u> </u>	34	-	43		51	ns
			5	N.	14	- <u>-</u> - 0	$V_{J,I,I}$	<b>-</b>	, i	W-10	ns
MM			6	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	1.190	29	V-T	37	7//	43	ns
Output Transition Time	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	2	Min.	x1 70	75		95	- 11	110	ns
(Figure 1)	100Y.	ONT	4.5	WEW.	- 1	15		19	- 1	22	ns
WW	W.100	COM	6		111.	13	Con	16	-	19	ns
Input Capacitance	C <sub>IN</sub>	C <sub>L</sub> = 50pF	-	-	M.W.	10	$\Gamma C_{\overline{\Omega},\overline{h}}$	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C <sub>PD</sub>	C <sub>L</sub> =15pF	5	- <	30	N.10	71.EO	)M.T	N -	WW	pF

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

WWW.100Y.CC

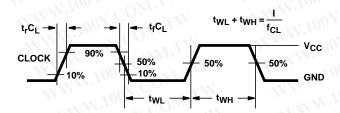
### Switching Specifications Input $t_r$ , $t_f = 6ns$ (Continued)

Maria	100 X.C.	TEST	Vcc	111	25°C	N.C.	-40°C 1	O 85°C	-55°C T	O 125°C		
PARAMETER	SYMBOL	CONDITIONS	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS	
HCT TYPES	V.	COM		WV	144.	on Y.		TW	2			
Propagation Delay Time (Figure 2)	t <sub>PLH,</sub> t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	W		40	$CO_N$	50	<u>-</u>	60	ns	
CP to Q1' Output	100	C <sub>L</sub> =15pF	5	- 1	17	u 100	1.0	M-TV	-	-	ns	
$Q_n$ to $Q_n + 1$	t <sub>PLH</sub> ,	C <sub>L</sub> = 50pF	4.5	- '	MAN	15	ONIC	19	N -	22	ns	
	tPHL	C <sub>L</sub> =15pF	5	-	6	1	00¥.C	-N.	[V-	-	ns	
MR to Q <sub>n</sub>	<sup>t</sup> PLH,	C <sub>L</sub> = 50pF	4.5	-	-W	40	. No.	50	777	60	ns	
	tPHL	C <sub>L</sub> =15pF	5	-	17	W-W	- 001	$C_{O_{M_1}}$	TW	-	ns	
Output Transition	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	4.5	N -	-	15	1.700	19	VI.	22	ns	
Input Capacitance	C <sub>IN</sub>	C <sub>L</sub> =15pF	$O_{M \cdot I}$	- X	-	10	W.700	10	Mir	10	pF	
Power Dissipation Capacitance (Notes 3, 4)	C <sub>PD</sub>	C <sub>L</sub> =15pF	COM	TW	30	W	WW.	00Y.C	$co_{M_{11}}$	W -	pF	

#### NOTES:

- 3. C<sub>PD</sub> is used to determine the dynamic power consumption, per package.
- 4.  $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$  where  $f_i = Input$  Frequency,  $C_L = Output$  Load Capacitance,  $V_{CC} = Supply$  Voltage.

### **Test Circuits and Waveforms**



CLOCK 2.7V 1.3V 1.3V GND GND

NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

FIGURE 1. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH

NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

FIGURE 2. HCT CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH

WWW.100Y.COM.TW

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

 $t_rC_L = 6ns$ 



15-Oct-2009 www.ti.com

### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3</sup>
5962-8945801EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD54HC4020F	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD54HC4020F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD54HCT4020F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD74HC4020E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC4020EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC4020M	ACTIVE	SOIC	COMIT	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4020M96	ACTIVE	SOIC	COM	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4020M96E4	ACTIVE	SOIC	D)M	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4020M96G4	ACTIVE	SOIC	OO Y DOOR	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4020ME4	ACTIVE	SOIC	100 D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4020MG4	ACTIVE	SOIC	10D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4020MT	ACTIVE	SOIC	N. D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4020MTE4	ACTIVE	SOIC	D 00	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4020MTG4	ACTIVE	SOIC	D 10	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4020E	ACTIVE	PDIP	N.	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HCT4020EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HCT4020M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4020M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4020M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4020M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4020ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4020MG4	ACTIVE	SOIC	M D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4020MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4020MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4020MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
	WWW	100 Y.C.	OM.TW		W	111.100Y.	COM.TW	Man

WWW.100 Y.CO



### PACKAGE OPTION ADDENDUM

15-Oct-2009 www.ti.com

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

> 特力材料886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www. 100y. com. tw

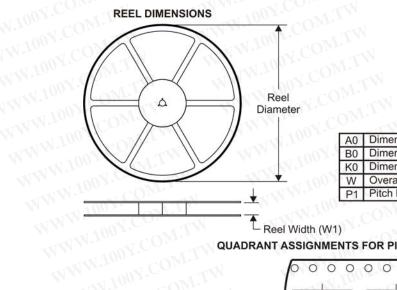
WWW.100Y.COM.TW

WWW.100Y.COM.TW

100Y.COM.TW

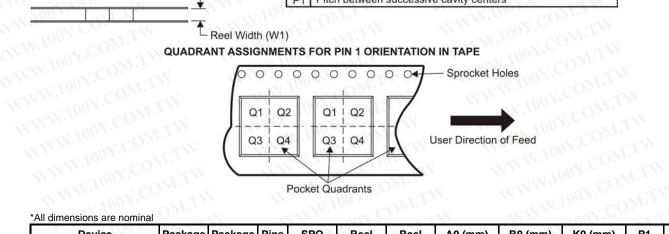


### TAPE AND REEL INFORMATION



### TAPE DIMENSIONS ★ K0 ◆ 0 $\Phi \Phi \Phi \Phi$ Φ 0 B<sub>0</sub> → A0 ← Cavity -

	A0	Dimension designed to accommodate the component width
١	B0	Dimension designed to accommodate the component length
7	K0	Dimension designed to accommodate the component thickness
¥	W	Overall width of the carrier tape
	P1	Pitch between successive cavity centers



# WWW.100Y.COM.TW ne -

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadran
CD74HC4020M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HCT4020M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

NWW.100Y.COM.TW

OX.COM.TW

WWW.100Y.COM.TW

100Y.COM.TW

WWW.100Y.COM.TW WWW.100Y.COM.TW 勝 特 力 材 料 886-3-5753170

胜特力电子(上海) 86-21-34970699

胜特力电子(深圳) 86-755-83298787

Http://www.100y.com.tw WWW.100Y.COM.TW

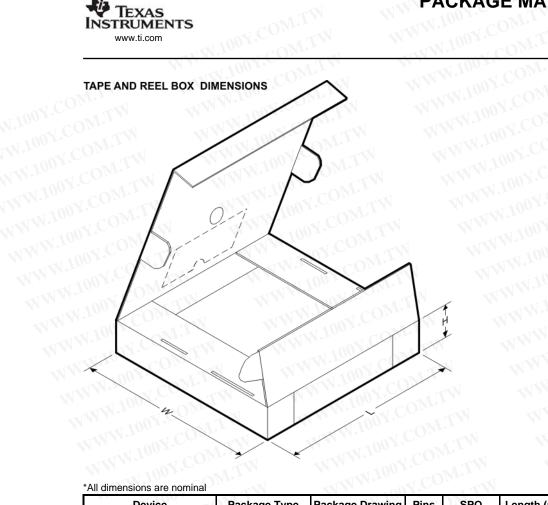
WWW.100Y.COM

WWW.100Y.COM.TW

WWW.1007.CC

WWW.100Y.COM.TW





WWW.100Y.CON.3

#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC4020M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74HCT4020M96	SOIC	D	16	2500	333.2	345.9	28.6

特力材料886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www. 100y. com. tw

MMM.To.

WWW.100Y.COM

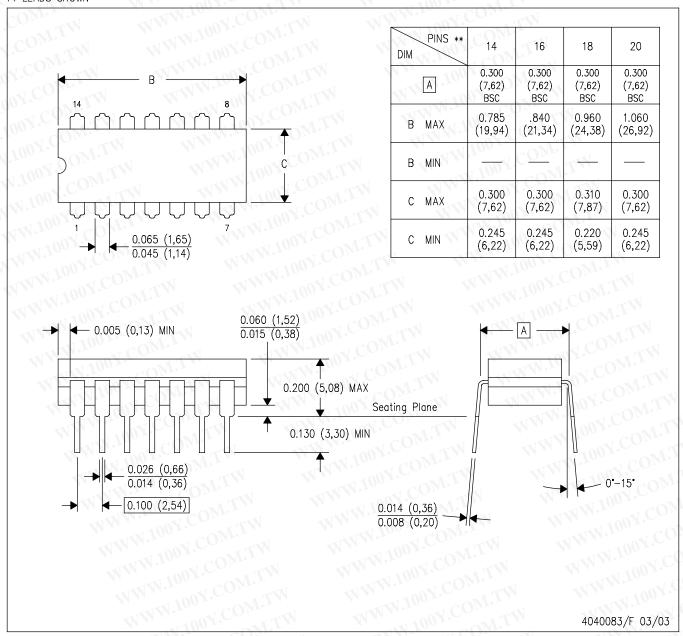
WWW.100Y.COM.TW

100Y.COM.TW

WWW.100Y.COM.TW

WWW.100X.C

### 14 LEADS SHOWN

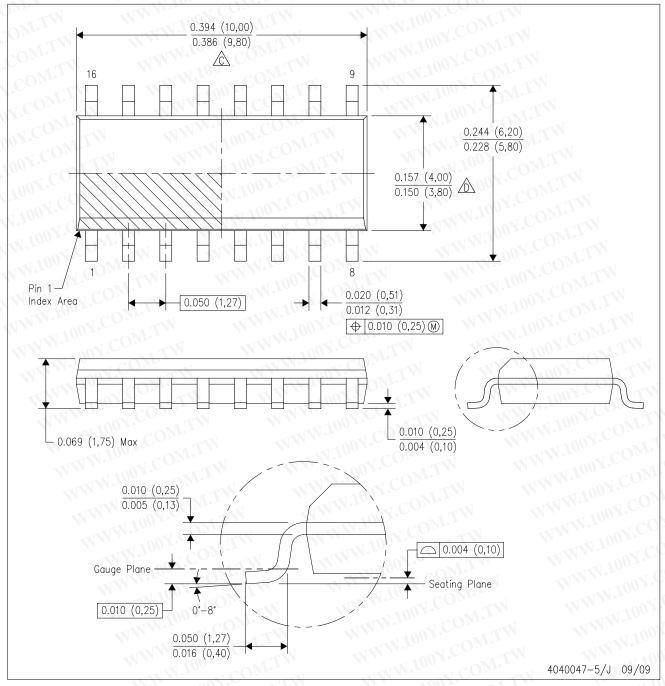


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## D (R-PDS0-G16)

### PLASTIC SMALL-OUTLINE PACKAGE



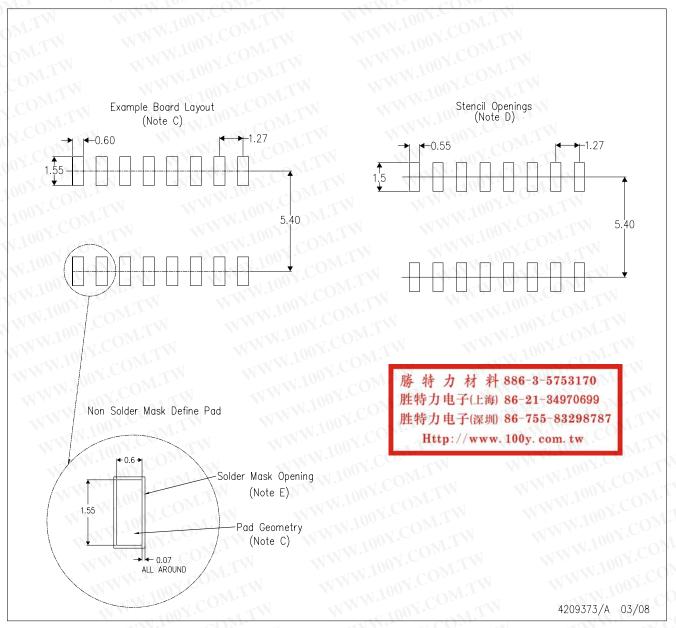
NOTES:

- All linear dimensions are in inches (millimeters).
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

  Body width does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end. WWW.100Y.COM
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



### D(R-PDSO-G16)



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525

WWW.100Y.C

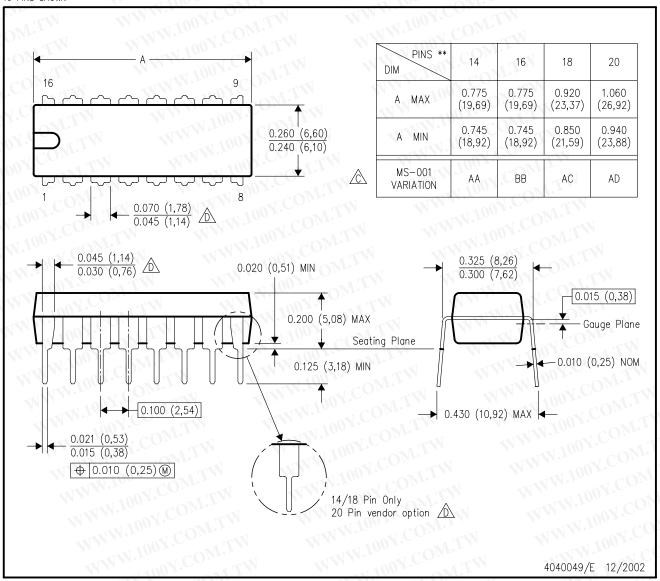
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw



WWW.100Y.CO

### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Applications **Products Amplifiers** amplifier.ti.com Audio **Data Converters** Automotive dataconverter.ti.com DLP® Products www.dlp.com Broadband DSP Digital Control dsp.ti.com Clocks and Timers Medical www.ti.com/clocks Interface Military interface.ti.com Optical Networking Logic logic.ti.com Power Mgmt Security power.ti.com Microcontrollers Telephony microcontroller.ti.com **RFID** Video & Imaging www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2009, Texas Instruments Incorporated